Product End-of-Life Disassembly Instructions

Product Category: Servers	
Marketing Name / Model **[List multiple models if applicable.]**	
HP ProLiant BL45p G2 8214 2.2GHz-2MB 4GB (2P) 408667-B21	
HP ProLiant BL45p G2 8216 2.4GHz-2MB 4GB (2P) 408668-B21	
HP ProLiant BL45p G2 8218 2.6GHz-2MB 4GB (2P) 408669-B21	

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Yes	10
Batteries	All types including standard alkaline and lithium coin or button style batteries Yes	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries NA	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps NA	
Cathode Ray Tubes (CRT)	NA	
Capacitors / condensers (Containing PCB/PCT)	No	
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	No	
External electrical cables and cords	No	
Gas Discharge Lamps	NA	
Plastics containing Brominated Flame Retardants	No	
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations. NA	
Components and waste containing asbestos	No	
Components, parts and materials containing refractory ceramic fibers	No	
Components, parts and materials containing radioactive substances	No	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

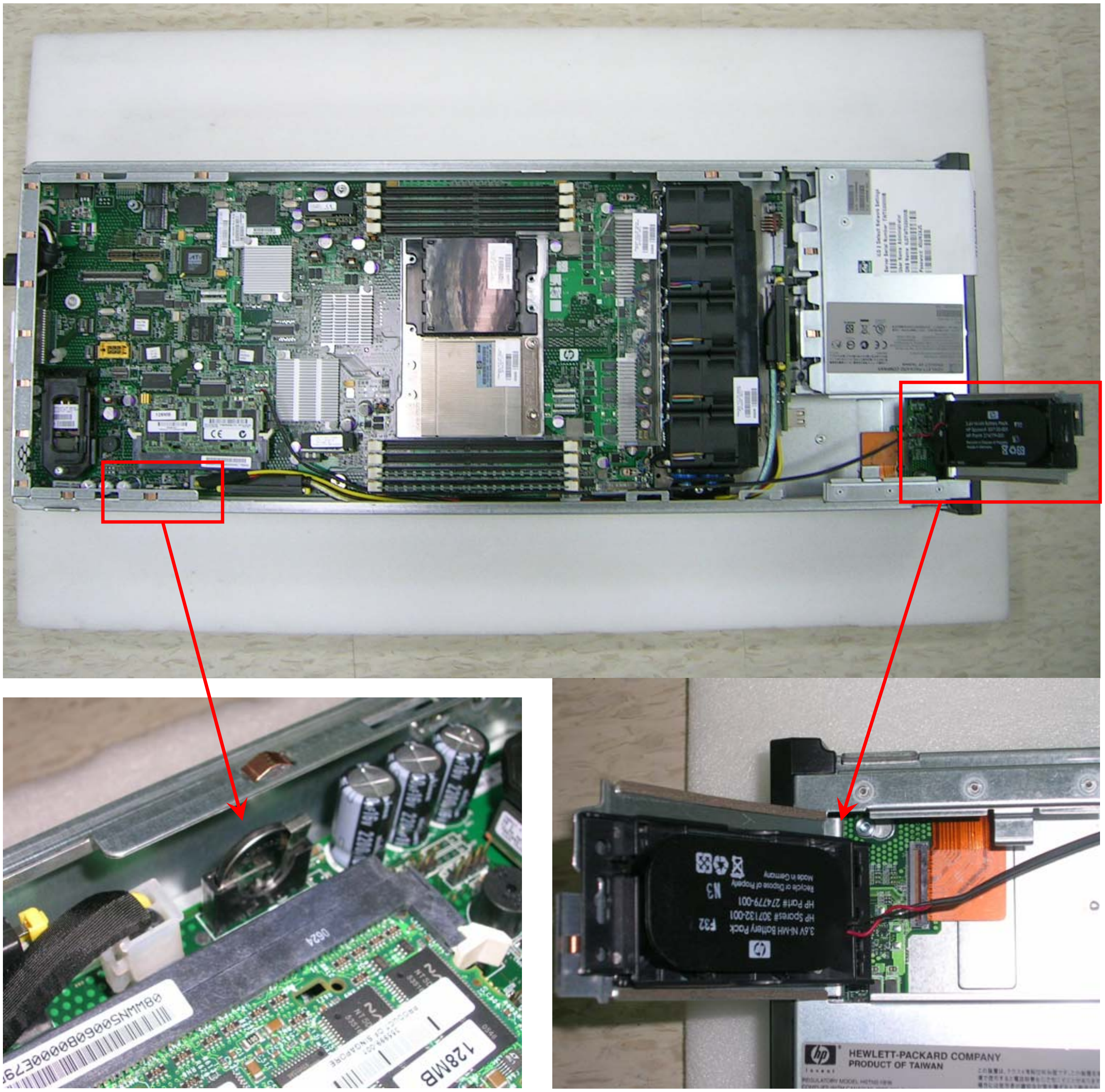
Tool Description	Tool Size (if applicable)
Torx Driver	T-15
Torx Driver	T-6
Flat Head Screw Driver	Medium

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. System board Battery – Remove top cover and locate the battery on system board. use hand to remove the battery and dispose of properly
2. BBWC - Remove latch of BBWC on SCSI CARD and use hand to remove the battery and dispose of properly
3.
4.
5.
6.
7.
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



There are no WEEE related items on BL45p G2 secondary side.